

## F7322-VB Datasheet

### Dual P-Channel 20V (D-S) MOSFET

#### PRODUCT SUMMARY

$V_{DS}$ (V)	$R_{DS(on)}$ ( $\Omega$ )	$I_D$ (A)
- 20	0.018 at $V_{GS} = - 4.5$ V	- 8.9
	0.022 at $V_{GS} = - 2.5$ V	- 8.1
	0.030 at $V_{GS} = - 1.8$ V	- 3.6

#### FEATURES

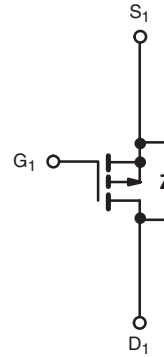
- Halogen-free According to IEC 61249-2-21 Definition
- Trench Power MOSFET
- Advanced High Cell Density Process
- Compliant to RoHS Directive 2002/95/EC



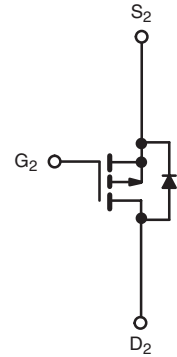
**RoHS**  
COMPLIANT  
HALOGEN  
**FREE**  
Available

#### APPLICATIONS

- Load Switching



P-Channel MOSFET



P-Channel MOSFET

#### ABSOLUTE MAXIMUM RATINGS $T_A = 25^\circ\text{C}$ , unless otherwise noted

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Parameter		Symbol	10 s	Steady State	Unit
Drain-Source Voltage		$V_{DS}$	- 20		V
Gate-Source Voltage		$V_{GS}$	$\pm 12$		
Continuous Drain Current ( $T_J = 150\text{ }^{\circ}\text{C}$ ) <sup>a</sup>	$T_A = 25\text{ }^{\circ}\text{C}$	$I_D$	- 8.9	- 6.7	A
	$T_A = 70\text{ }^{\circ}\text{C}$		- 7.1	- 5.4	
Pulsed Drain Current		$I_{DM}$	- 30		
Continuous Source Current (Diode Conduction) <sup>a</sup>		$I_S$	- 1.7	- 0.9	W
Maximum Power Dissipation <sup>a</sup>	$T_A = 25\text{ }^{\circ}\text{C}$	$P_D$	2.0	1.1	
	$T_A = 70\text{ }^{\circ}\text{C}$		1.3	0.7	
Operating Junction and Storage Temperature Range		$T_J, T_{stg}$	- 55 to 150		$^{\circ}\text{C}$

#### THERMAL RESISTANCE RATINGS

Parameter	Symbol	Typical	Maximum	Unit
Maximum Junction-to-Ambient <sup>a</sup>	$R_{thJA}$	46	62.5	$^\circ\text{C/W}$
		80	110	
Maximum Junction-to-Foot (Drain)	$R_{thJF}$	24	32	

Notes:

a. Surface Mounted on 1" x 1" FR4 board.

<b>SPECIFICATIONS</b> $T_J = 25\text{ }^{\circ}\text{C}$ , unless otherwise noted						
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit
<b>Static</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -350\text{ }\mu\text{A}$	-0.4		-1.0	V
Gate-Body Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 8\text{ V}$			$\pm 100$	nA
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -20\text{ V}$ , $V_{GS} = 0\text{ V}$			-1	$\mu\text{A}$
		$V_{DS} = -20\text{ V}$ , $V_{GS} = 0\text{ V}$ , $T_J = 55\text{ }^{\circ}\text{C}$			-5	
On-State Drain Current <sup>a</sup>	$I_{D(on)}$	$V_{DS} = -5\text{ V}$ , $V_{GS} = -4.5\text{ V}$	-30			A
Drain-Source On-State Resistance <sup>a</sup>	$R_{DS(on)}$	$V_{GS} = -4.5\text{ V}$ , $I_D = -8.9\text{ A}$		0.018		$\Omega$
		$V_{GS} = -2.5\text{ V}$ , $I_D = -8.1\text{ A}$		0.022		
		$V_{GS} = -1.8\text{ V}$ , $I_D = -3.6\text{ A}$		0.030		
Forward Transconductance <sup>a</sup>	$g_{fs}$	$V_{DS} = -10\text{ V}$ , $I_D = -8.9\text{ A}$		26		S
Diode Forward Voltage <sup>a</sup>	$V_{SD}$	$I_S = -1.7\text{ A}$ , $V_{GS} = 0\text{ V}$		-0.7	-1.2	V
<b>Dynamic<sup>b</sup></b>						
Total Gate Charge	$Q_g$	$V_{DS} = -10\text{ V}$ , $V_{GS} = -4.5\text{ V}$ , $I_D = -8.9\text{ A}$		34.5	52	nC
Gate-Source Charge	$Q_{gs}$			5.1		
Gate-Drain Charge	$Q_{gd}$			9.6		
Gate Resistance	$R_g$			9		$\Omega$
Turn-On Delay Time	$t_{d(on)}$	$V_{DD} = -10\text{ V}$ , $R_L = 6\text{ }\Omega$ $I_D \approx -1\text{ A}$ , $V_{GEN} = -4.5\text{ V}$ , $R_g = 6\text{ }\Omega$		25	40	ns
Rise Time	$t_r$			46	70	
Turn-Off Delay Time	$t_{d(off)}$			230	345	
Fall Time	$t_f$			155	235	
Source-Drain Reverse Recovery Time	$t_{rr}$	$I_F = -1.7\text{ A}$ , $dI/dt = 100\text{ A}/\mu\text{s}$		128	200	

Notes:

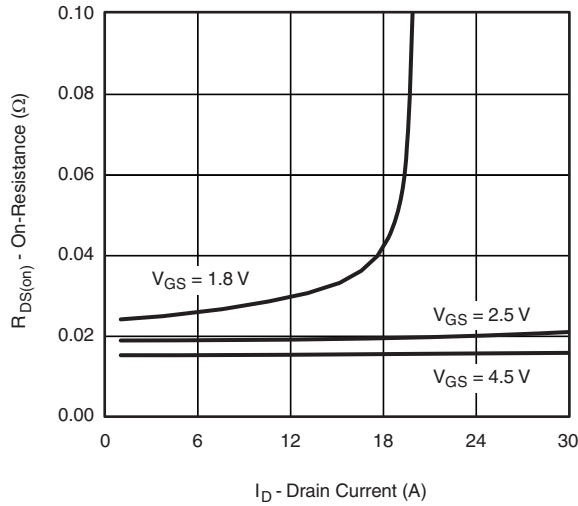
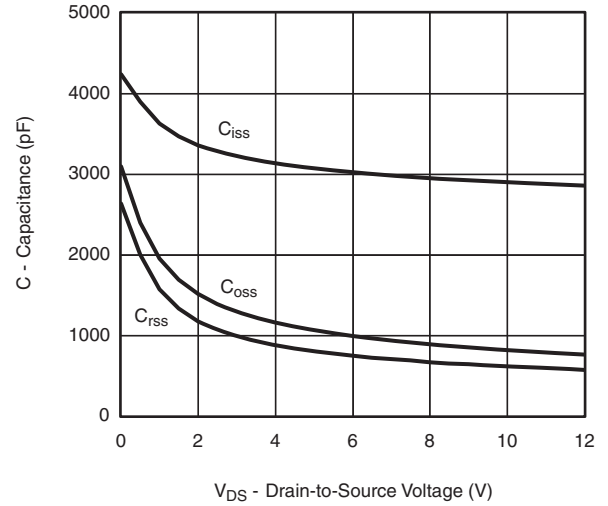
a. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .

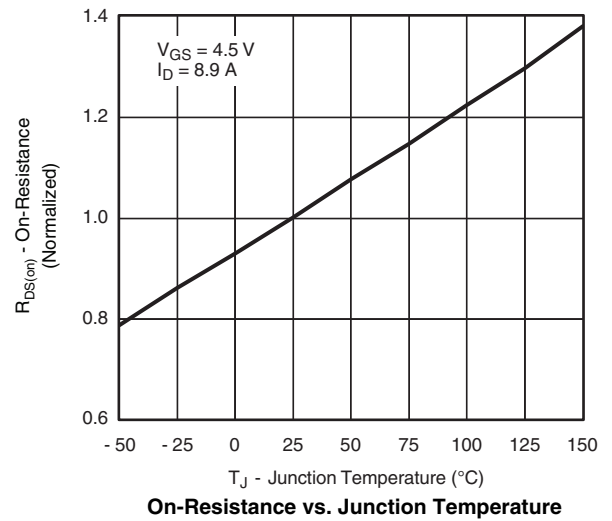
b. Guaranteed by design, not subject to production testing.

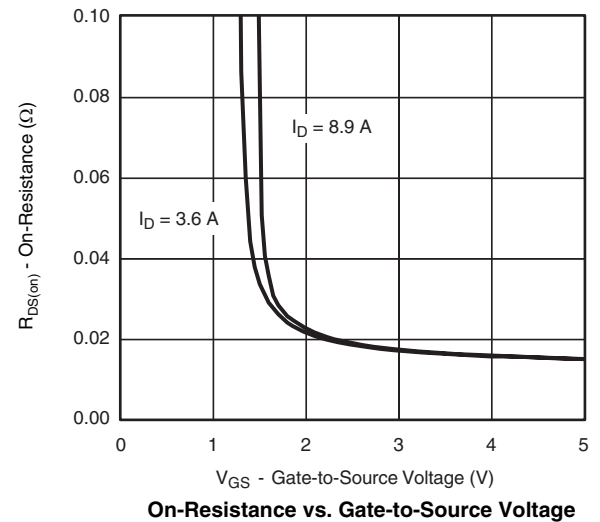
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

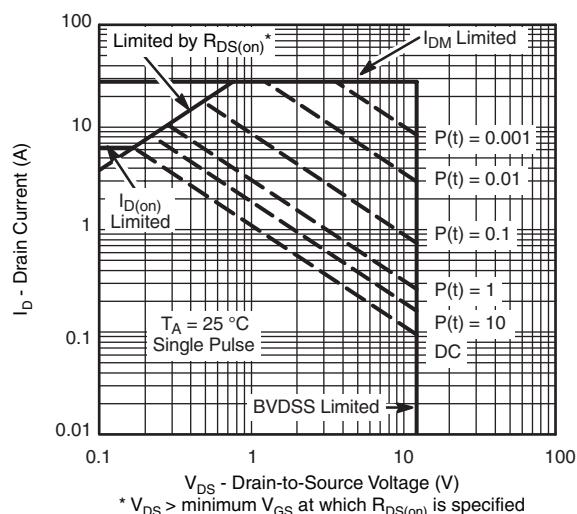
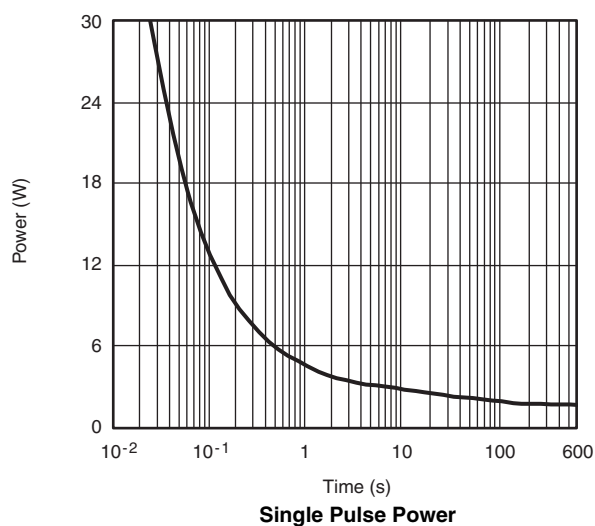
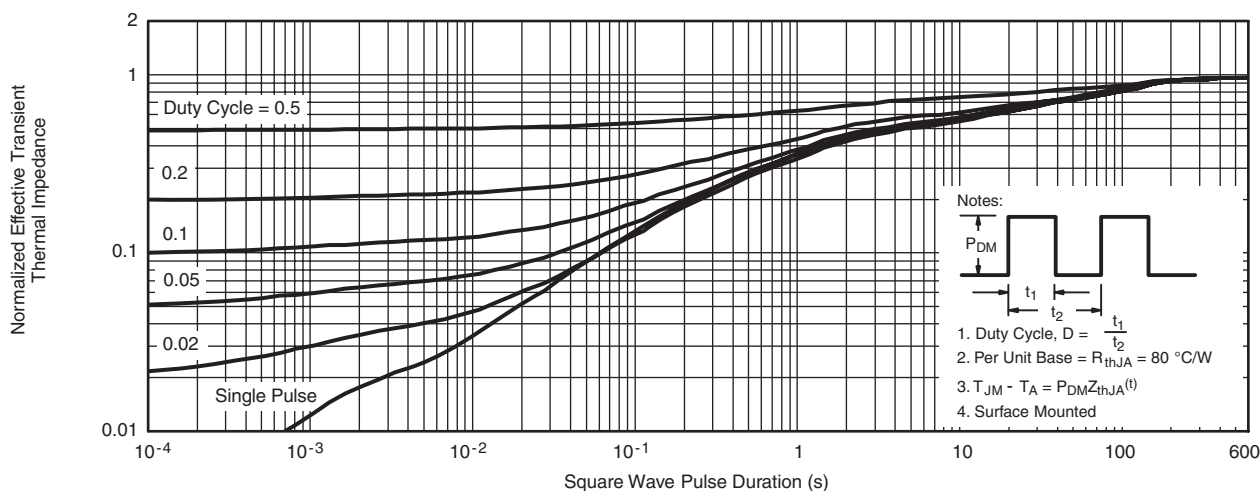
## TYPICAL CHARACTERISTICS $25\text{ }^{\circ}\text{C}$ unless otherwise noted



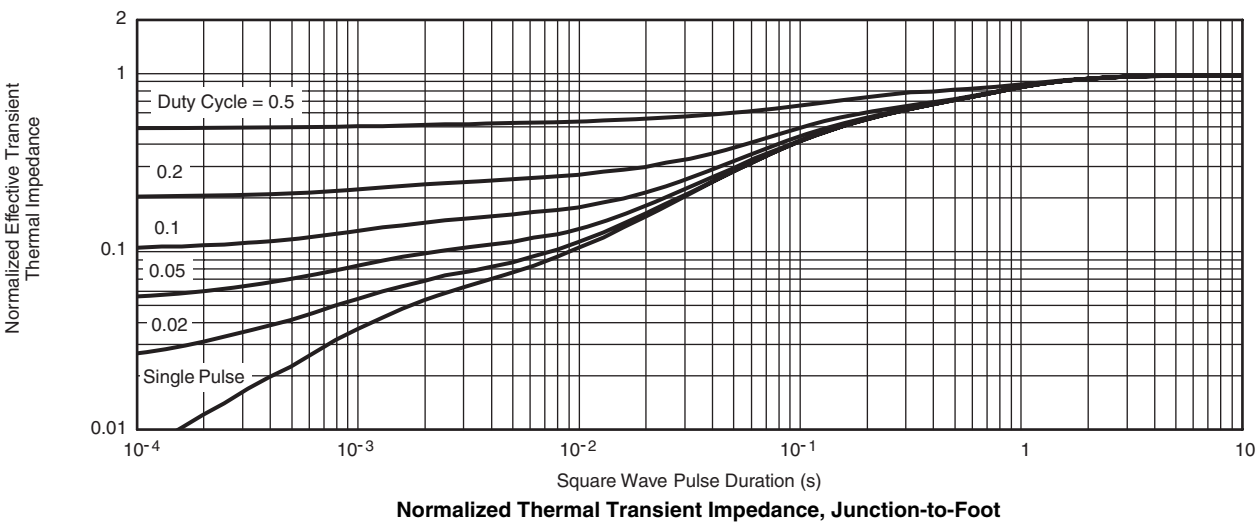
**TYPICAL CHARACTERISTICS** 25 °C unless otherwise noted

**On-Resistance vs. Drain Current**

**Capacitance**

**Gate Charge**

**On-Resistance vs. Junction Temperature**

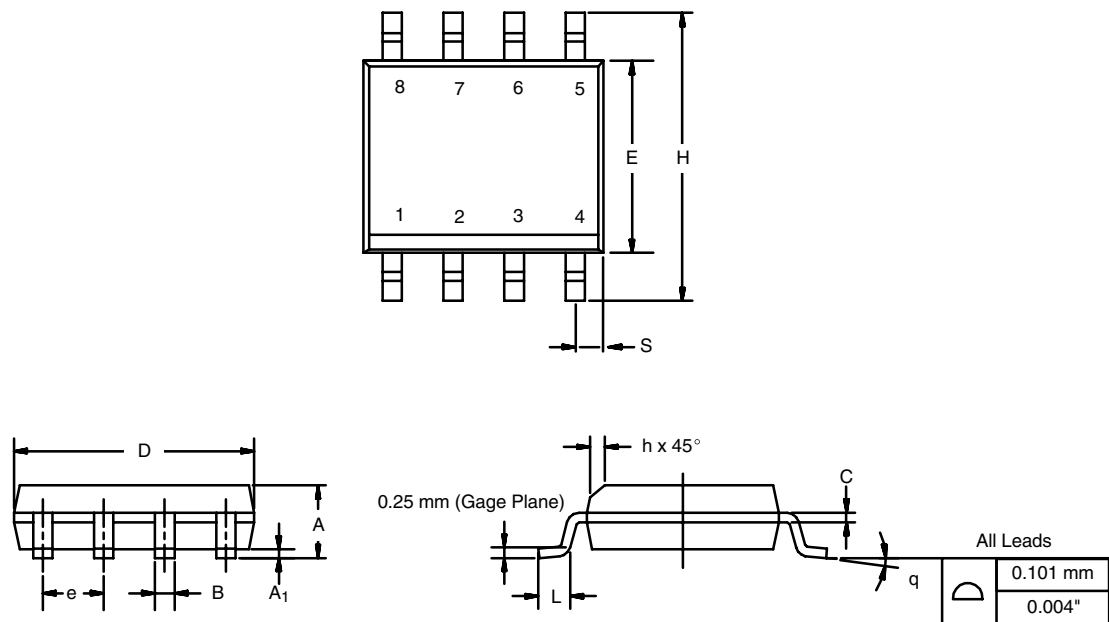
**Source-Drain Diode Forward Voltage**

**On-Resistance vs. Gate-to-Source Voltage**

**TYPICAL CHARACTERISTICS** 25 °C unless otherwise noted

**Safe Operating Area, Junction-to-Ambient**

**Normalized Thermal Transient Impedance, Junction-to-Ambient**

**TYPICAL CHARACTERISTICS** 25 °C unless otherwise noted

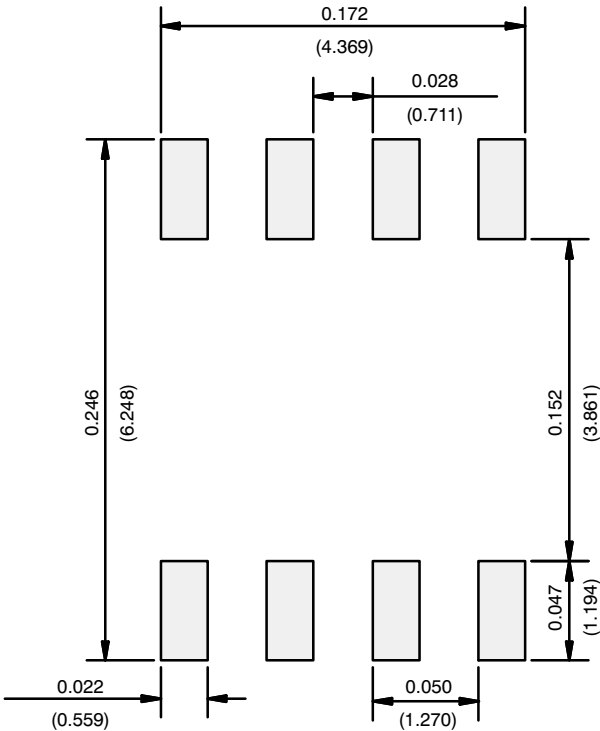


**SOIC (NARROW): 8-LEAD**  
JEDEC Part Number: MS-012



DIM	MILLIMETERS		INCHES	
	Min	Max	Min	Max
A	1.35	1.75	0.053	0.069
A <sub>1</sub>	0.10	0.20	0.004	0.008
B	0.35	0.51	0.014	0.020
C	0.19	0.25	0.0075	0.010
D	4.80	5.00	0.189	0.196
E	3.80	4.00	0.150	0.157
e	1.27 BSC		0.050 BSC	
H	5.80	6.20	0.228	0.244
h	0.25	0.50	0.010	0.020
L	0.50	0.93	0.020	0.037
q	0°	8°	0°	8°
S	0.44	0.64	0.018	0.026
ECN: C-06527-Rev. I, 11-Sep-06				
DWG: 5498				

RECOMMENDED MINIMUM PADS FOR SO-8



Recommended Minimum Pads  
Dimensions in Inches/(mm)

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